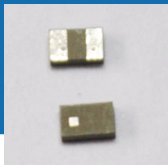


Low profile Compact 2.4 GHz Ceramic Chip Antenna



ACAG0201-2450-T



2.0 x 1.25 x 0.6mm
RoHS/RoHS II Compliant
MSL = 1

FEATURES

- Gain of 2.7dBi
- VSWR ≤ 2.0
- Miniature form factor 2.0 x 1.25 x 0.6mm
- Made using LTCC technology (low temperature co-fired ceramic)
- Omni-directional

APPLICATIONS

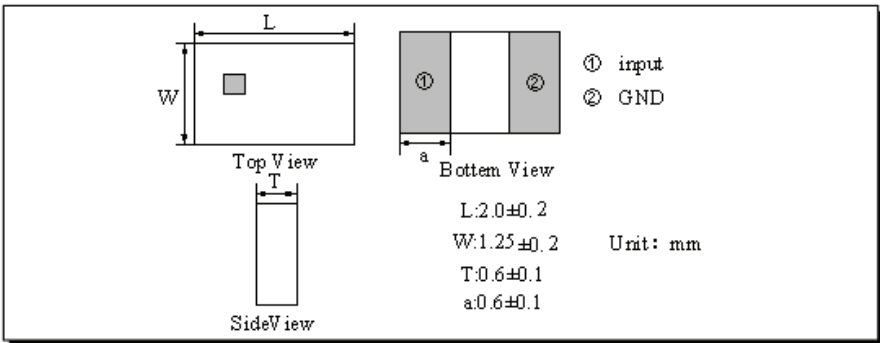
- IoT and wearable
- Wi-Fi
- Bluetooth/BLE
- ISM band

ELECTRICAL CHARACTERISTICS

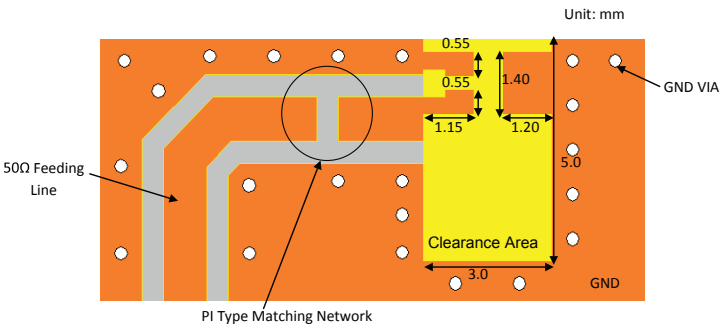
Item	Specification
Centre Frequency (After matching)	2450 MHz
Bandwidth	65 MHz typ
VSWR	≤ 2.0
Impedance	50 Ω
Gain	2.7 dBi
Azimuth	Omni-directional
Polarization	Linear
Operating Temperature range	-40°C ~ + 85°C

MECHANICAL DIMENSIONS (mm)

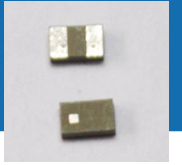
Antenna Dimensions



Layout Dimensions



Low profile Compact 2.4 GHz Ceramic Chip Antenna

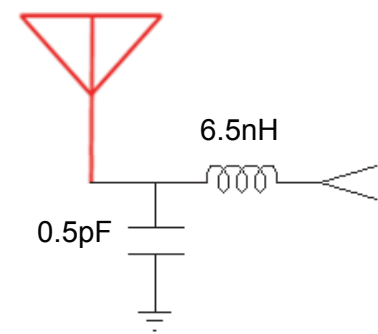
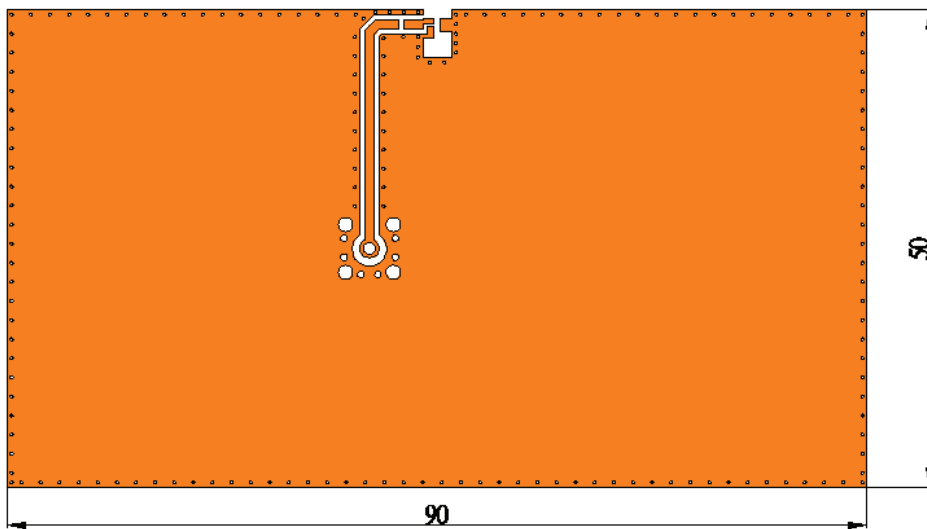


ACAG0201-2450-T

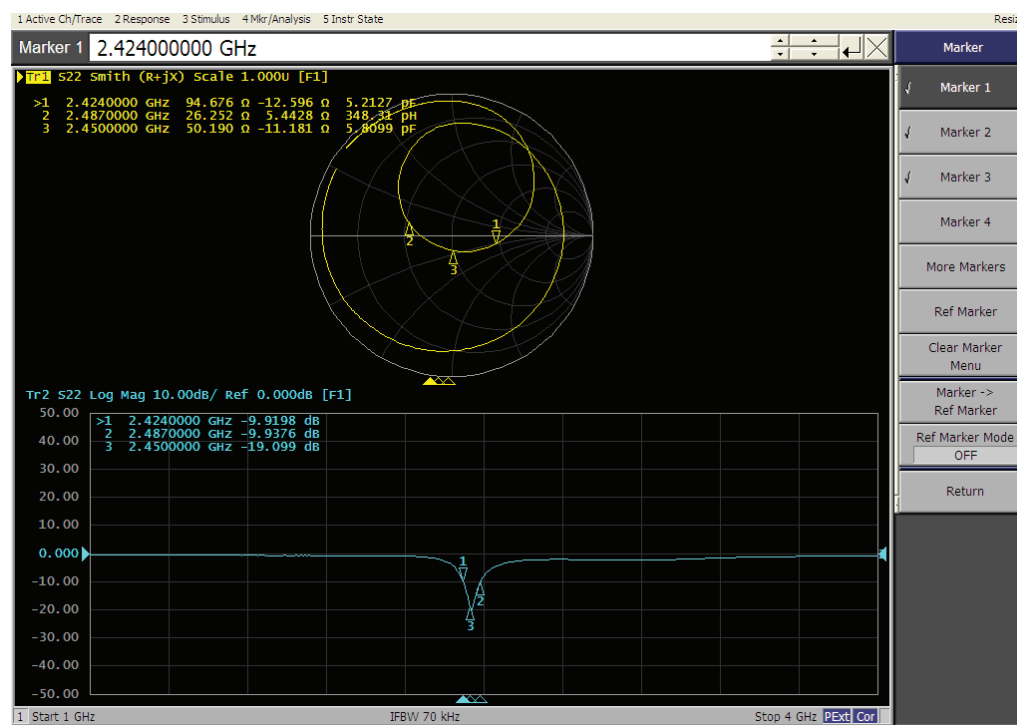


2.0 x 1.25 x 0.6mm
RoHS/RoHS II Compliant
MSL = 1

EVALUATION BOARD AND MATCHING CIRCUITS



ANTENNA RESPONSE – SMITH CHART AND RETURN LOSS S11

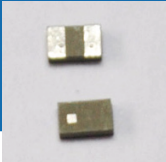


Low profile Compact 2.4 GHz Ceramic Chip Antenna

ACAG0201-2450-T

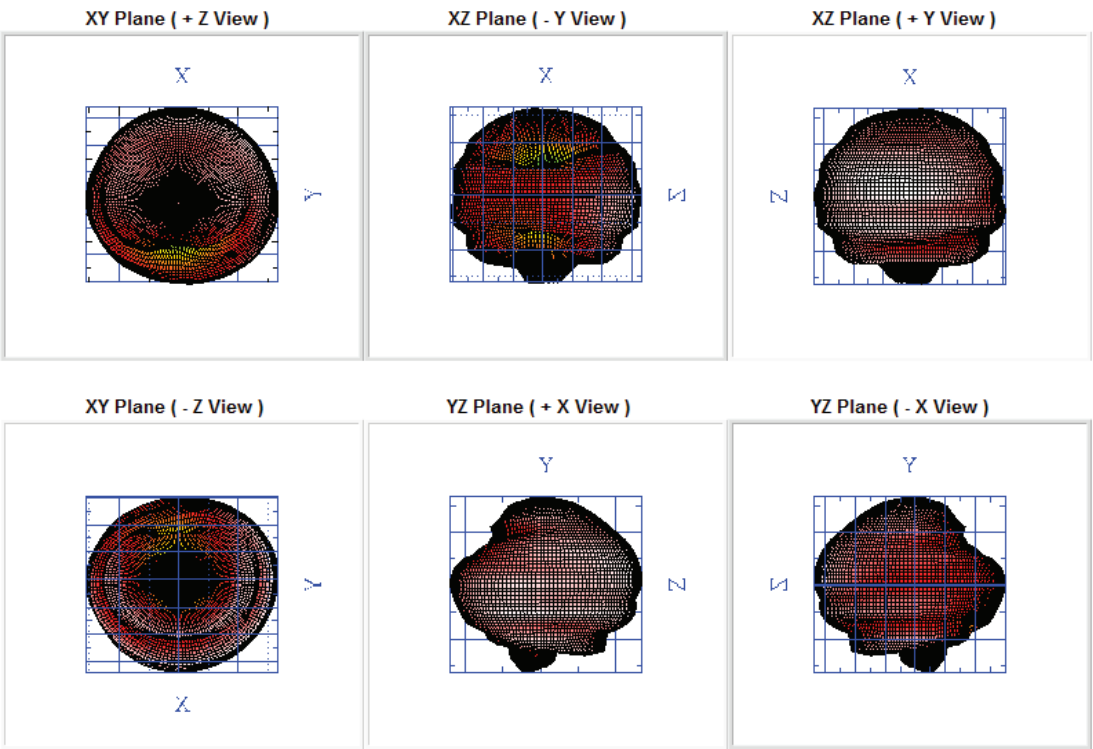
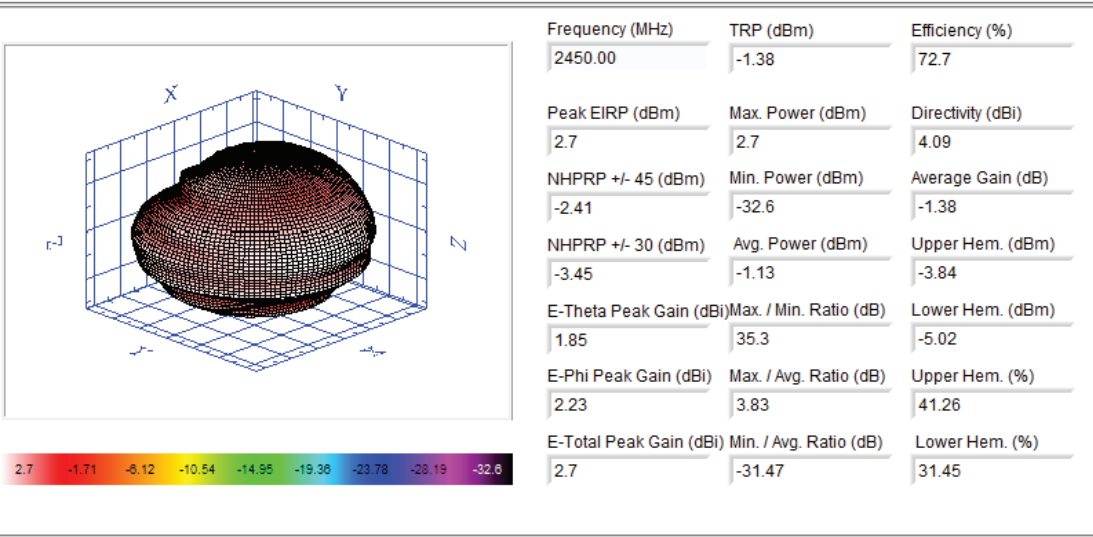
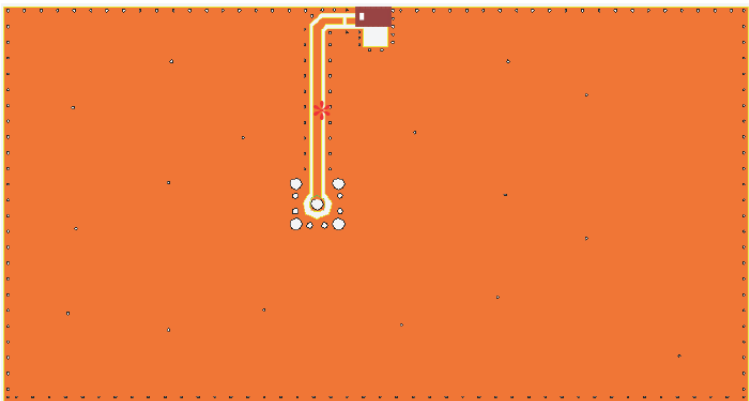
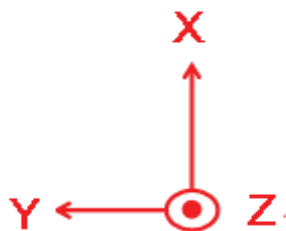


2.0 x 1.25 x 0.6mm
RoHS/RoHS II Compliant
MSL = 1



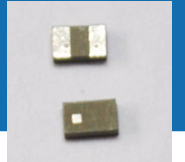
RADIATION PATTERNS

Coordinates



Low profile Compact 2.4 GHz Ceramic Chip Antenna

ACAG0201-2450-T



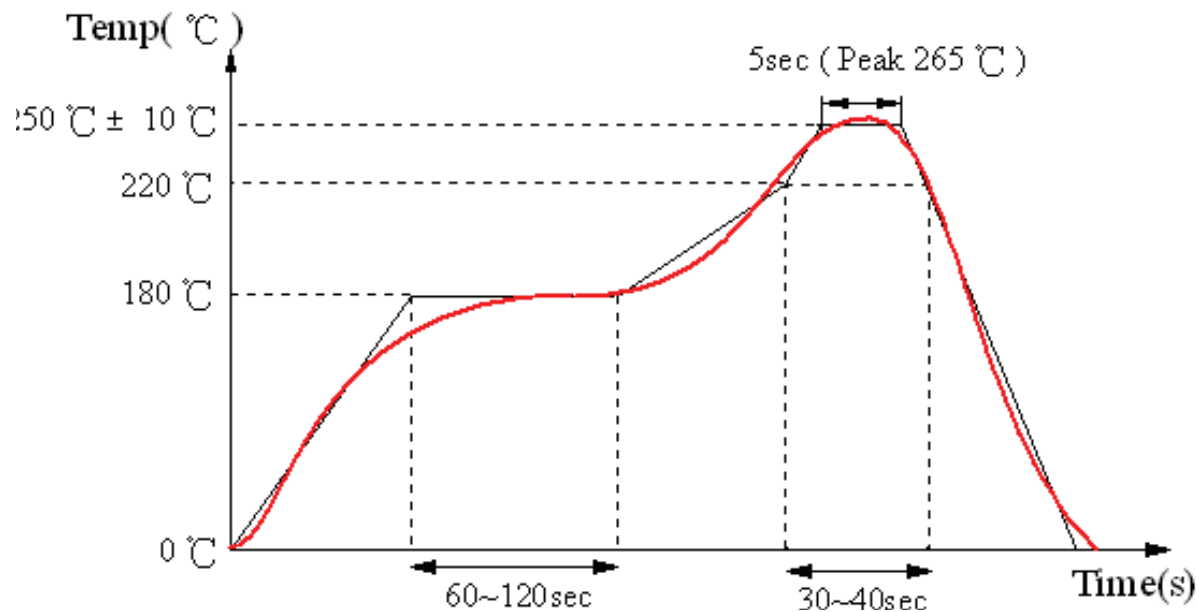
2.0 x 1.25 x 0.6mm



RoHS/RoHS II Compliant

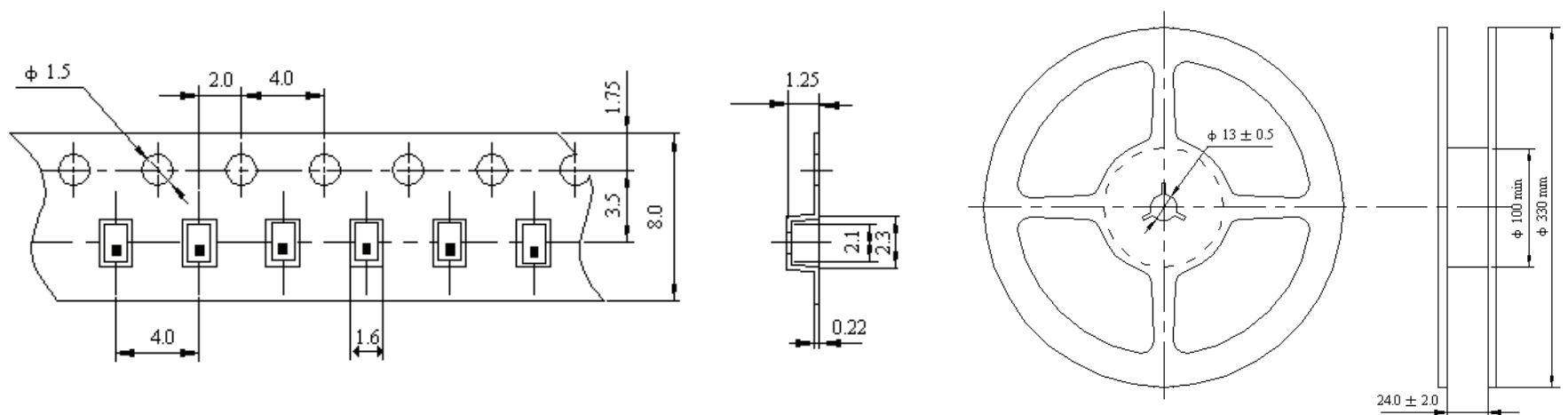
MSL = 1

REFLOW SOLDERING STANDARD CONDITION



PACKAGING

Reel (4000 pcs/Reel)



Dimensions: mm

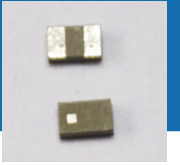
Storage Temperature Range : <30 degree C, Humidity : <60%RH

MSL-1

Oxidizable, 12 months in a vacuum sealed bag.

Once opened, please repack the unused items within 168 hours by re-seal package treatment.

Low profile Compact 2.4 GHz Ceramic Chip Antenna



ACAG0201-2450-T



2.0 x 1.25 x 0.6mm

RoHS/RoHS II Compliant

MSL = 1

CAUTIONS

1. Static voltage

Static voltage between signal & ground may cause deterioration & destruction of the component. Please avoid static voltage.

2. Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

3. Soldering

Only leads of the component may be soldered. Please avoid soldering to any other part of the component, such as on the patterns as this will change the performance of the antenna.